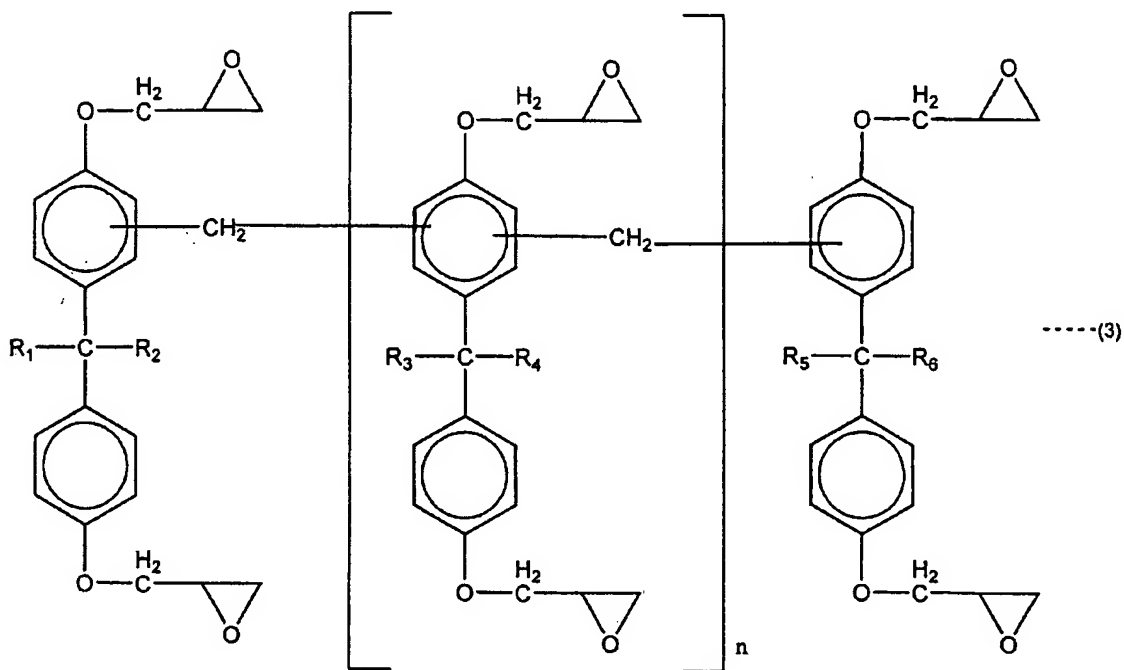


## AMENDMENTS TO THE CLAIMS

**1 to 8. (Canceled)**

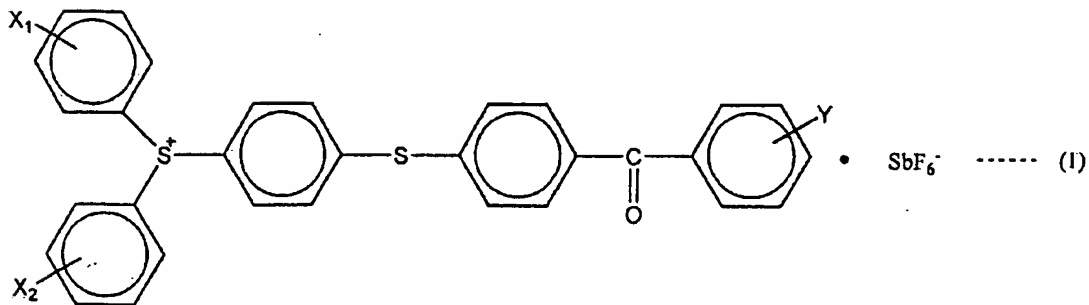
**9. (New)** A photosensitive resin composition comprising:

a multi-functional bisphenol A novolak epoxy resin, a functionality of which is 5-functional groups or more and represented by general formula (3) shown below:



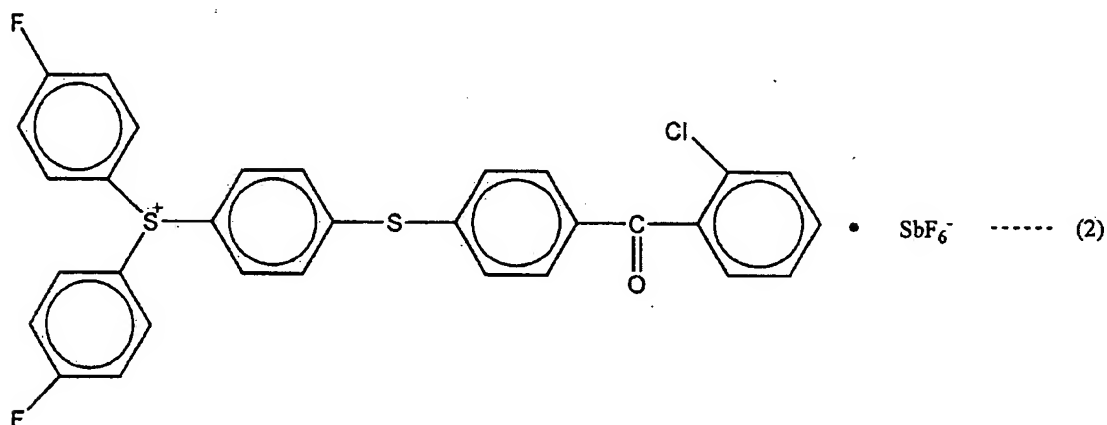
(in the formula,  $R_1$  to  $R_6$  are independently H or  $CH_3$ , respectively,  $n$  indicates zero or larger integer); and

a cation polymerization initiator represented by general formula (1) shown below:



(in the formula, X<sub>1</sub> and X<sub>2</sub> indicate a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond, respectively, and they may be identical to or different from one another, and Y indicates a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond).

10. (New) The photosensitive resin composition according to claim 9, wherein the cation polymerization initiator is a compound represented by chemical formula (2) shown below:



11. (New) The photosensitive resin composition according to claim 9, further comprising a linear polymeric 2-functional epoxy resin.

12. (New) The photosensitive resin composition according to claim 9, further comprising a naphthol sensitizer.

13. (New) The photosensitive resin composition according to claim 9, further comprising  $\gamma$ -butyrolactone.

14. (New) A photosensitive resin composition laminate comprising:

a photosensitive resin composition layer obtained from the photosensitive resin composition according to claim 9; and  
a protective film,  
wherein at least one side of the photosensitive resin composition layer is protected with the protective film.

**15. (New)** A method of forming a pattern comprising the steps of:

applying the photosensitive resin composition according to claim 9 on a desired base and then drying the photosensitive resin composition;  
exposing a radiation beam on a photosensitive resin composition layer to form given resin patterns;  
developing the beam-exposed photosensitive resin composition layer; and  
heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

**16. (New)** A method of forming a pattern comprising the steps of:

peeling the protective film away from the photosensitive resin composition laminate according to claim 14;  
attaching a resulting photosensitive resin composition layer on a desired base;  
exposing a radiation beam on the photosensitive resin composition layer to form a given pattern;  
developing the beam-exposed photosensitive resin composition layer; and  
heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

**17. (New)** The photosensitive resin composition according to claim 9, wherein a content of the multi-functional bisphenol A novolak epoxy resin, a functionality of which is 5-functional groups or more is 80 to 99.9 mass% based on a solid content of the photosensitive resin composition.